

# PolarHV™ HiPerFET

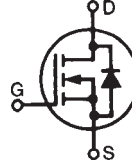
## Power MOSFET

(Electrically Isolated Tab)

**IXFP 8N50PM**

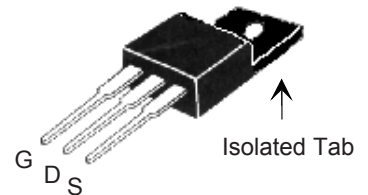
$$\begin{aligned} V_{DSS} &= 500 \text{ V} \\ I_{D25} &= 4.4 \text{ A} \\ R_{DS(on)} &\leq 0.8 \text{ } \Omega \\ trr &\leq 200 \text{ ns} \end{aligned}$$

N-Channel Enhancement Mode  
Avalanche Rated  
Fast Intrinsic Diode



Symbol	Test Conditions	Maximum Ratings	
$V_{DSS}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$	500	V
$V_{DGR}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$ ; $R_{GS} = 1 \text{ M}\Omega$	500	V
$V_{GS}$	Continuous	$\pm 30$	V
$V_{GSM}$	Transient	$\pm 40$	V
$I_{D25}$	$T_C = 25^\circ\text{C}$	4.4	A
$I_{DM}$	$T_C = 25^\circ\text{C}$ , pulse width limited by $T_{JM}$	14	A
$I_{AR}$	$T_C = 25^\circ\text{C}$	8	A
$E_{AR}$	$T_C = 25^\circ\text{C}$	20	mJ
$E_{AS}$	$T_C = 25^\circ\text{C}$	300	mJ
$dv/dt$	$I_S \leq I_{DM}$ , $di/dt \leq 100 \text{ A}/\mu\text{s}$ , $V_{DD} \leq V_{DSS}$ , $T_J \leq 150^\circ\text{C}$ , $R_G = 18 \text{ } \Omega$	10	V/ns
$P_D$	$T_C = 25^\circ\text{C}$	42	W
$T_J$		-55 ... +150	$^\circ\text{C}$
$T_{JM}$		150	$^\circ\text{C}$
$T_{stg}$		-55 ... +150	$^\circ\text{C}$
$T_L$	1.6 mm (0.062 in.) from case for 10 s	300	$^\circ\text{C}$
$T_{SOLD}$	Plastic body for 10 s	260	$^\circ\text{C}$
$M_d$	Mounting torque	1.13/10	Nm/lb.in.
<b>Weight</b>		4	g

OVERMOLDED TO-220  
(IXTP...M) OUTLINE



G = Gate      D = Drain  
S = Source

### Features

- † Plastic overmolded tab for electrical isolation
- † International standard package
- † Unclamped Inductive Switching (UIS) rated
- † Low package inductance
  - easy to drive and to protect
- † Fast Intrinsic Diode

### Advantages

- † Easy to mount
- † Space savings
- † High power density

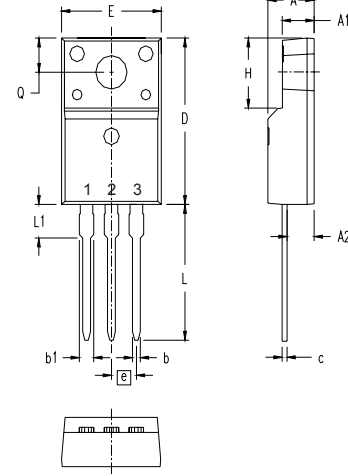
Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
$BV_{DSS}$	$V_{GS} = 0 \text{ V}$ , $I_D = 250 \text{ } \mu\text{A}$	500		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 1 \text{ mA}$	3.0		5.5 V
$I_{GSS}$	$V_{GS} = \pm 30 \text{ V}_{DC}$ , $V_{DS} = 0$			$\pm 100 \text{ nA}$
$I_{DSS}$	$V_{DS} = V_{DSS}$ , $V_{GS} = 0 \text{ V}$ , $T_J = 125^\circ\text{C}$			5 $\mu\text{A}$ 500 $\mu\text{A}$
$R_{DS(on)}$	$V_{GS} = 10 \text{ V}$ , $I_D = 4 \text{ A}$ Pulse test, $t \leq 300 \text{ } \mu\text{s}$ , duty cycle $d \leq 2 \%$			0.8 $\Omega$

Symbol	Test Conditions	Characteristic Values		
		(T <sub>J</sub> = 25° C unless otherwise specified)		
		Min.	Typ.	Max.
<b>g<sub>fs</sub></b>	V <sub>DS</sub> = 10 V; I <sub>D</sub> = 4 A	5	8	S
<b>C<sub>iss</sub></b>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz		1050	pF
<b>C<sub>oss</sub></b>			120	pF
<b>C<sub>rss</sub></b>			12	pF
<b>t<sub>d(on)</sub></b>	V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 0.5 V <sub>DSS</sub> , I <sub>D</sub> = 8 A R <sub>G</sub> = 18 Ω (External)		22	ns
<b>t<sub>r</sub></b>			28	ns
<b>t<sub>d(off)</sub></b>			65	ns
<b>t<sub>f</sub></b>			23	ns
<b>Q<sub>g(on)</sub></b>	V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 0.5 V <sub>DSS</sub> , I <sub>D</sub> = 4 A		20	nC
<b>Q<sub>gs</sub></b>			7	nC
<b>Q<sub>gd</sub></b>			7	nC
<b>R<sub>thJS</sub></b>				3.0 °C/W

### Source-Drain Diode

Symbol	Test Conditions	Characteristic Values		
		(T <sub>J</sub> = 25° C, unless otherwise specified)		
		Min.	Typ.	Max.
<b>I<sub>S</sub></b>	V <sub>GS</sub> = 0 V			8 A
<b>I<sub>SM</sub></b>	Repetitive			14 A
<b>V<sub>SD</sub></b>	I <sub>F</sub> = I <sub>S</sub> , V <sub>GS</sub> = 0 V, Pulse test, t ≤ 300 μs, duty cycle d ≤ 2 %			1.5 V
<b>t<sub>rr</sub></b>	I <sub>F</sub> = 8 A, V <sub>GS</sub> = 0V, V <sub>R</sub> = 100V -di/dt = 100 A/μs		0.25	200 ns
<b>Q<sub>RM</sub></b>				2 μC
<b>I<sub>RM</sub></b>				2

### ISOLATED TO-220 (IXTP...M)



Terminals: 1 - Gate  
2 - Drain (Collector)  
3 - Source (Emitter)

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.177	.193	4.50	4.90
A1	.092	.108	2.34	2.74
A2	.101	.117	2.56	2.96
b	.028	.035	0.70	0.90
b1	.050	.058	1.27	1.47
c	.018	.024	0.45	0.60
D	.617	.633	15.67	16.07
E	.392	.408	9.96	10.36
e	.100 BSC		2.54 BSC	
H	.255	.271	6.48	6.88
L	.499	.523	12.68	13.28
L1	.119	.135	3.03	3.43
∅P	.121	.129	3.08	3.28
Q	.126	.134	3.20	3.40

### PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

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